



Distributor of CTS Electronic Components: Excellent Integrated System Limited

Datasheet of LBE66B1CB - HEATSINK PWR .31"H BLACK TO-220

Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com

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Stocking Distributor

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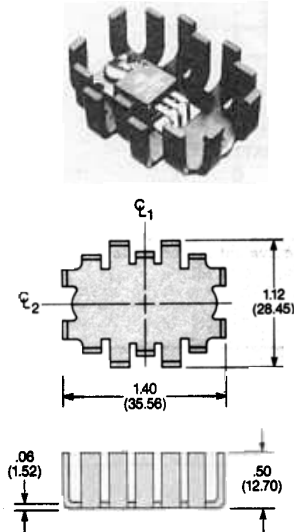
SECTION 2

HEAT DISSIPATORS FOR PLASTIC CASE, CASE-MOUNTED SEMICONDUCTORS

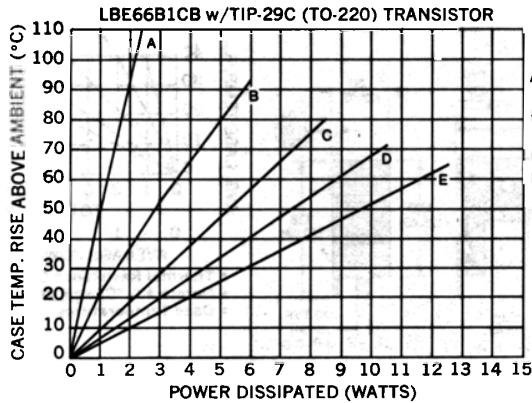
Board-mounted heat dissipators

- These compact, high-performance heat dissipators have exceptional volume/thermal efficiency ratios, making them especially effective where board space is limited and power levels are high.
- A wide range of hole patterns is available for single and multiple semiconductor mounting.
- Various finger heights in the LA, LB and UP Series optimize power dissipation, permit tailoring the heat dissipator to match vertical height requirements.

LB-B1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

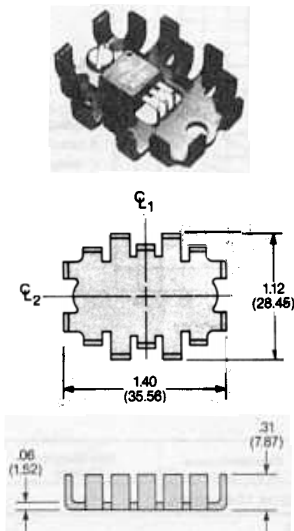
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

Ordering Information

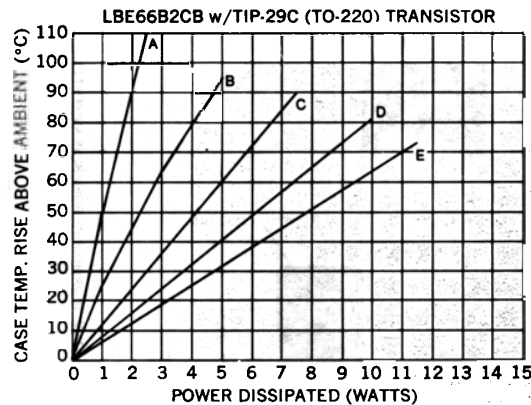
IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LB66B1-76U LBE66B1U	LB66B1-76CB LBE66B1CB	LB66B2-76B LBE66B1B	LB66B1-76 LBE66B1	Undrilled TO-126, TO-220	1	6.2

Note: See page iv for other finishes.

LB-B2 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Derate 0.4 °C/watt for unplated part in natural convection only.
- Derate 3.0 °C/watt for Insulube® part in natural convection only.

Ordering Information

IERC PART NO.				Semiconductor Accommodated	Hole patt. ref. no. (see pg. 2-27)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Insulube® 448			
LB66B2-76U LBE66B2U	LB66B2-76CB LBE66B2CB	LB66B2-76B LBE66B2B	LB66B2-76 LBE66B2	Undrilled TO-126, TO-220	1	4.8

Note: See page iv for other finishes.